



Material Content Data Sheet



Sales Product Name		BSP317P H6327		Issued		25. September 2017		
MA#		MA001073634						
Package		PG-SOT223-4-21		Weight*		113.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.068	0.06		598	
	non noble metal	tin	7440-31-5	0.018	0.02		154	
	inorganic material	silicon	7440-21-3	0.770	0.68	0.76	6776	7528
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		446	
	non noble metal	chromium	7440-47-3	0.152	0.13		1339	
	non noble metal	copper	7440-50-8	50.489	44.44	44.62	444418	446292
wire	non noble metal	copper	7440-50-8	0.020	0.02	0.02	174	174
encapsulation	organic material	carbon black	1333-86-4	0.601	0.53		5286	
	plastics	epoxy resin	-	9.008	7.93		79291	
	inorganic material	silicondioxide	60676-86-0	50.445	44.40	52.86	444027	528604
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12886	12886
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4516	4516
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com